

SMD ■ B EASV2713RGBA0



Features

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Multi-color type.
- Pb-free.
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).

Descriptions

- The SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

Applications

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGaInP	Brilliant Red	Water Clear
InGaN	Brilliant Green	
InGaN	Blue	

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	R6:25 GH:25 BH:25	mA
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	R6:60 GH:95 BH:100	mA
Power Dissipation	P_d	R6:60 GH:95 BH:95	mW
Operating Temperature	T_{opr}	-40 ~ +85	℃
Storage Temperature	T_{stg}	-40 ~ +90	℃
Electrostatic Discharge(HBM)	ESD_{HBM}	R6:2000 GH:2000 BH:2000	V
Soldering Temperature	T_{sol}	Reflow Soldering : 260 ℃ for 10 sec. Hand Soldering : 350 ℃ for 3 sec.	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I _v	R6	45.0	-----	180	mcd
		GH	112	-----	450	
		BH	28.5	-----	112	
Viewing Angle	2θ _{1/2}	-----	120	-----	deg	
Peak Wavelength	λ _p	R6	-----	632	-----	nm
		GH	-----	518	-----	
		BH	-----	468	-----	
Dominant Wavelength	λ _d	R6	615	-----	630	nm
		GH	510	-----	540	
		BH	460	-----	480	
Spectrum Radiation Bandwidth	Δλ	R6	-----	20	-----	nm
		GH	-----	35	-----	
		BH	-----	25	-----	
Forward Voltage	V _F	R6	1.7	2.0	2.4	V
		GH	2.7	3.3	3.7	
		BH	2.7	3.3	3.7	
Reverse Current	I _R	R6	-----	-----	10	μA

Note:

1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Dominant Wavelength: ±1nm
3. Tolerance of Forward Voltage: ±0.1V

R6

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
P	45.0	72.0	mcd	I _F =20mA
Q	72.0	112		
R	112	180		

GH

Bin Range of Luminous Intensity

Bin Code.	Min.	Max.	Unit	Condition
R	112	180	mcd	I _F =20mA
S	180	285		
T	285	450		

BH

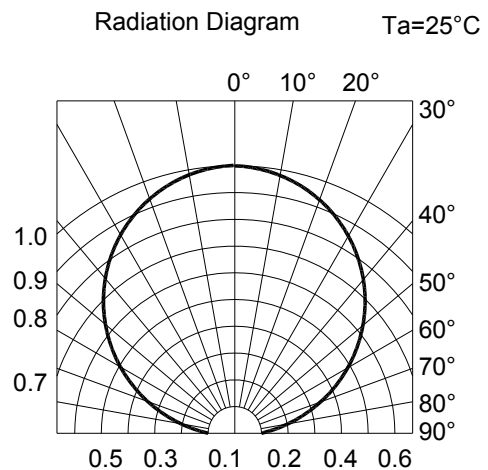
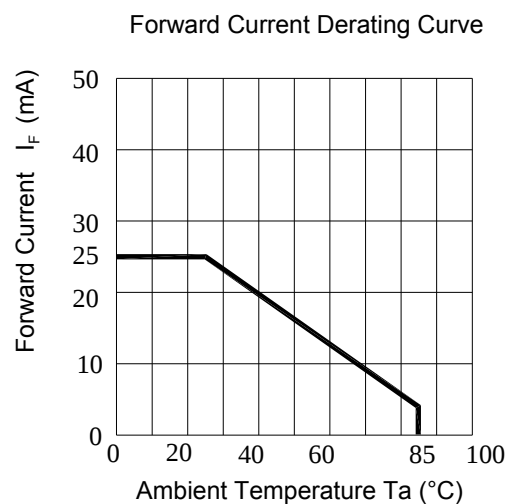
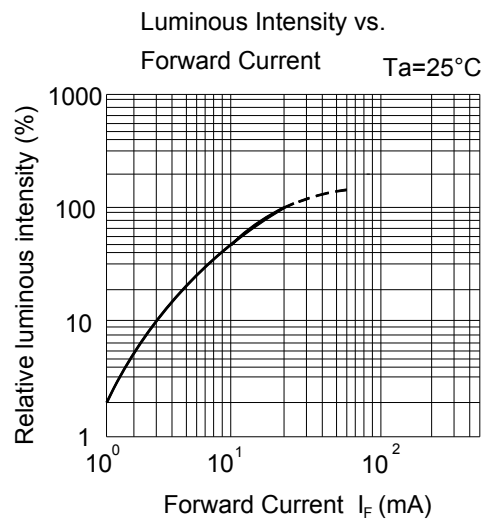
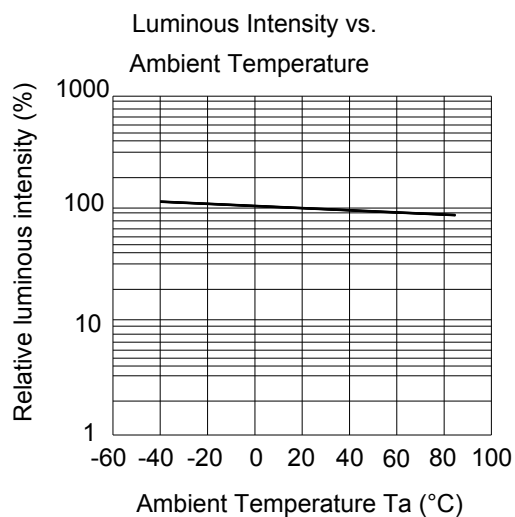
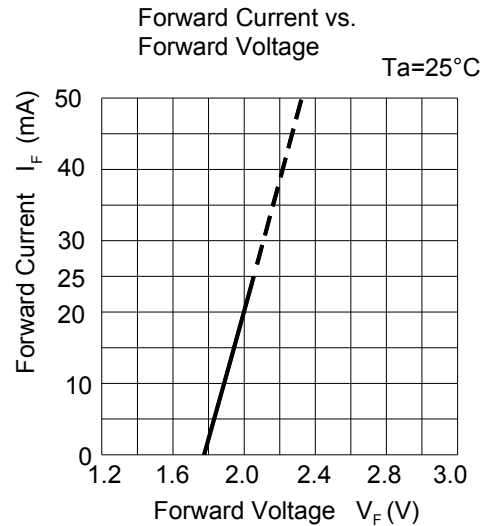
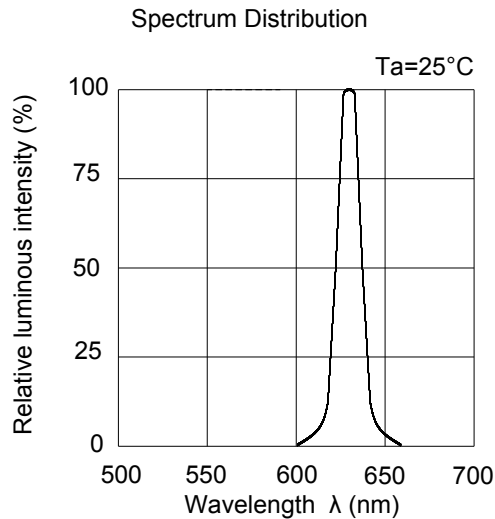
Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
N	28.5	45.0	mcd	I _F =20mA
P	45.0	72.0		
Q	72.0	112		

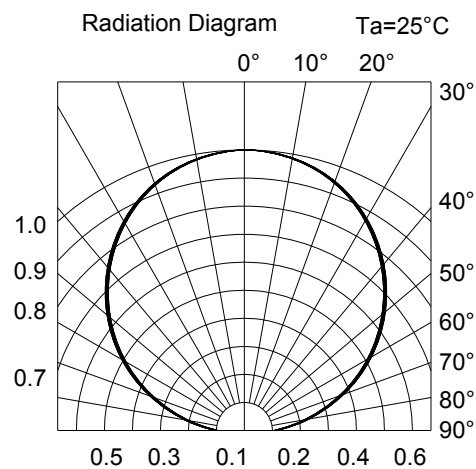
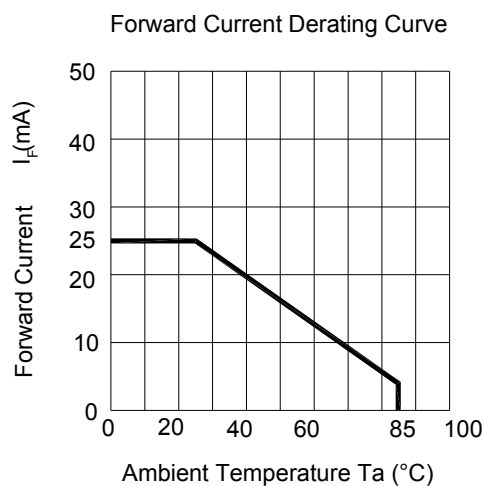
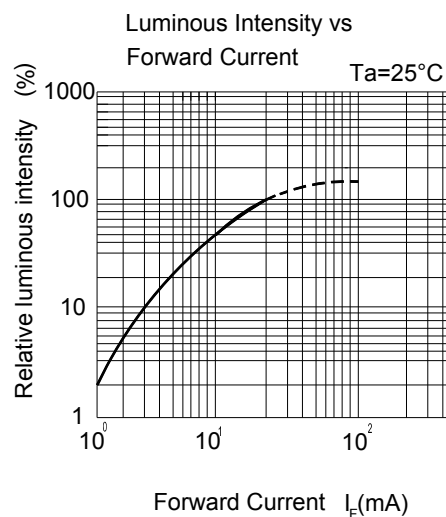
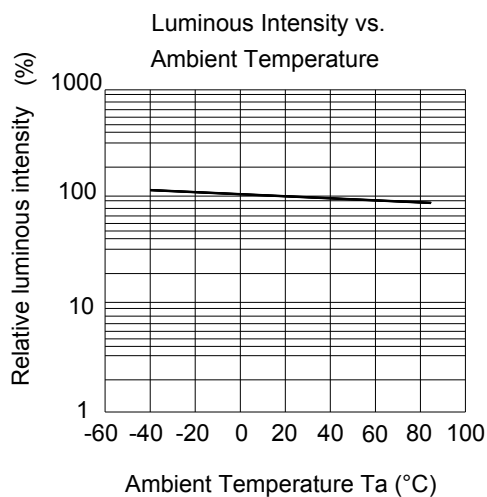
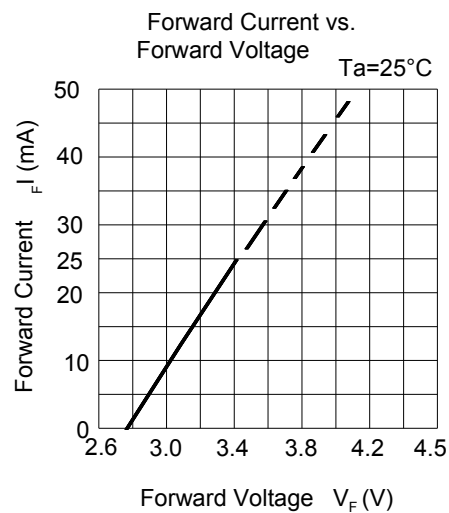
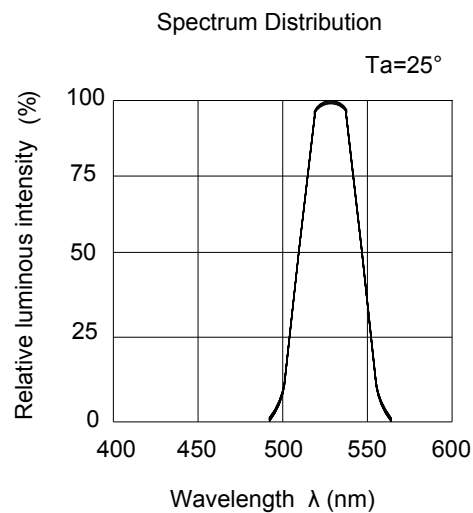
Note:

Tolerance of Luminous Intensity: ±11%

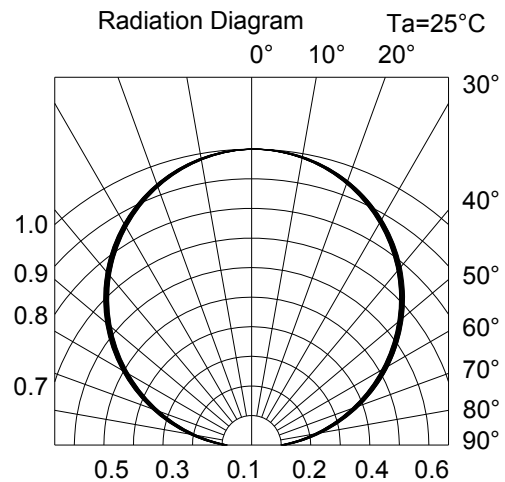
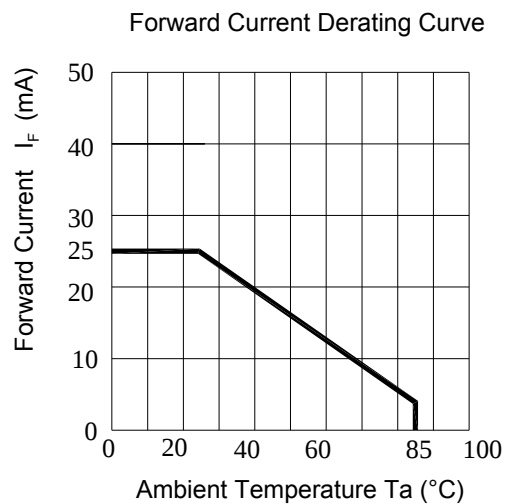
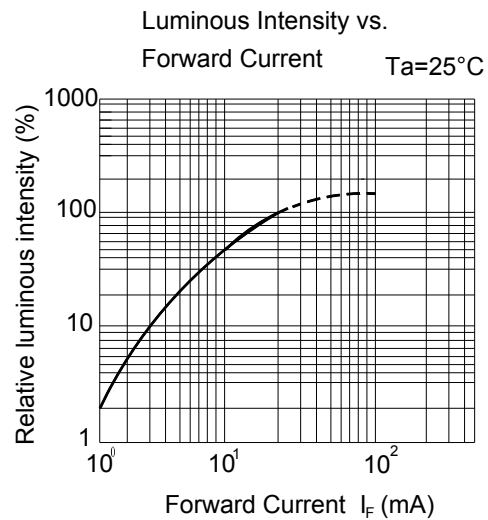
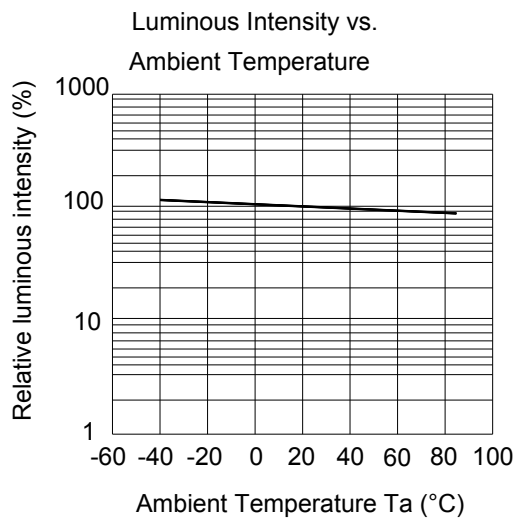
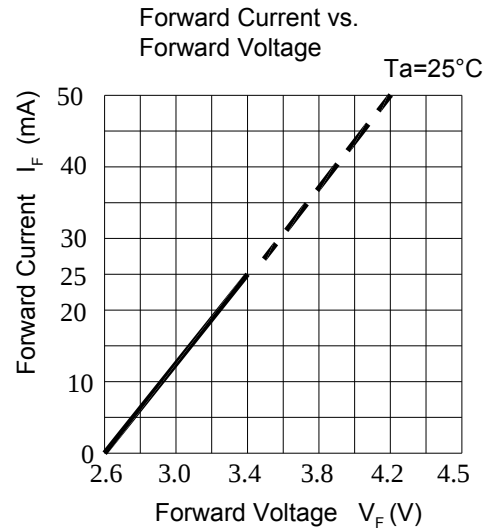
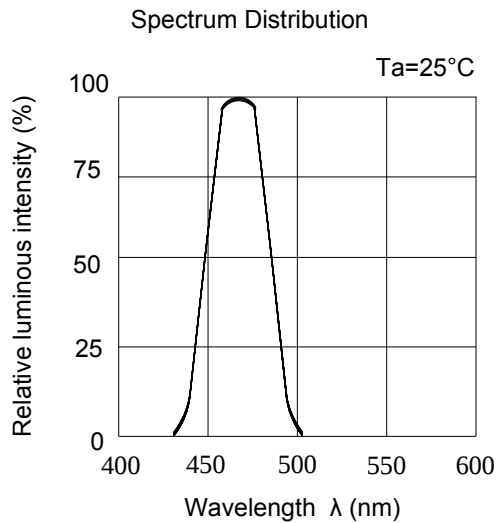
Typical Electro-Optical Characteristics Curves R6

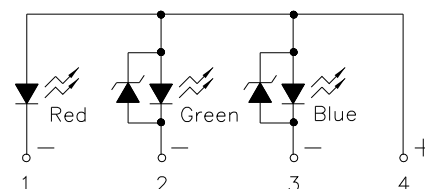


Typical Electro-Optical Characteristics Curves GH



Typical Electro-Optical Characteristics Curves BH



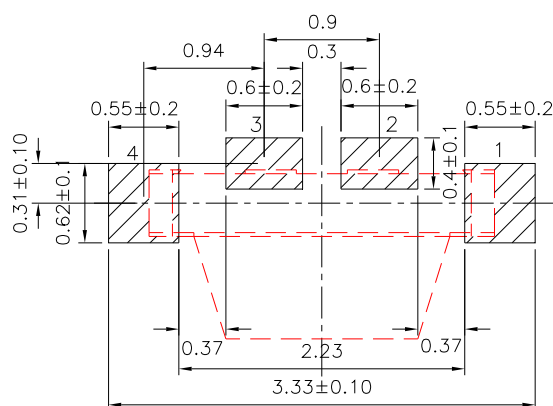
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Technical drawing of a mechanical part showing a top view and a side view.

The top view is a rectangle with a width of 2.0 and a length of 1.5.

The side view shows a profile with a total height of 1.35 and a top flange thickness of 0.5. The profile has a central vertical dashed line and two sloped sides.

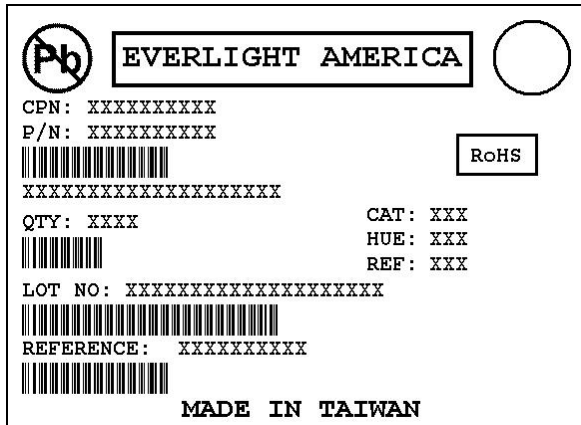
Figure 1 is a schematic diagram of the structure of the micro-structure. The diagram shows a cross-section of a micro-structure with various layers and dimensions. The top layer is labeled "Au Plating Area" (hatched pattern). Below it is a "Green Mask" (dotted pattern). The structure is divided into four main regions labeled 1, 2, 3, and 4. Dimensions are given in millimeters. The total width is 2.0 mm, divided into two 1.0 mm sections. The total height is 0.34 ± 0.10 mm. Other dimensions include 0.35, 0.4, 0.41, 0.45, 0.5, 0.16, 0.1, 0.2, and 0.4. A legend at the bottom identifies the hatched pattern as "Au Plating Area" and the dotted pattern as "Green Mask".



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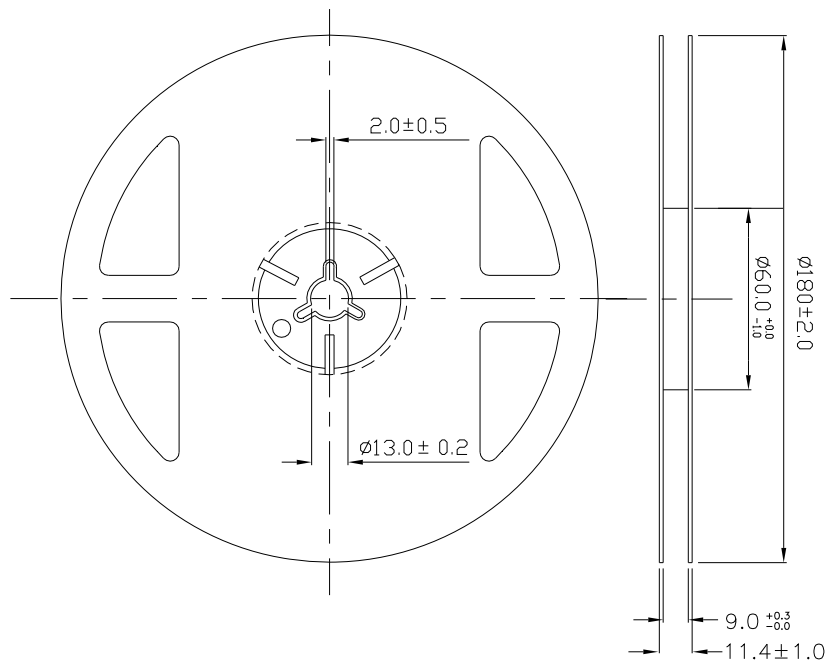
Moisture Resistant Packing Materials

Label Explanation



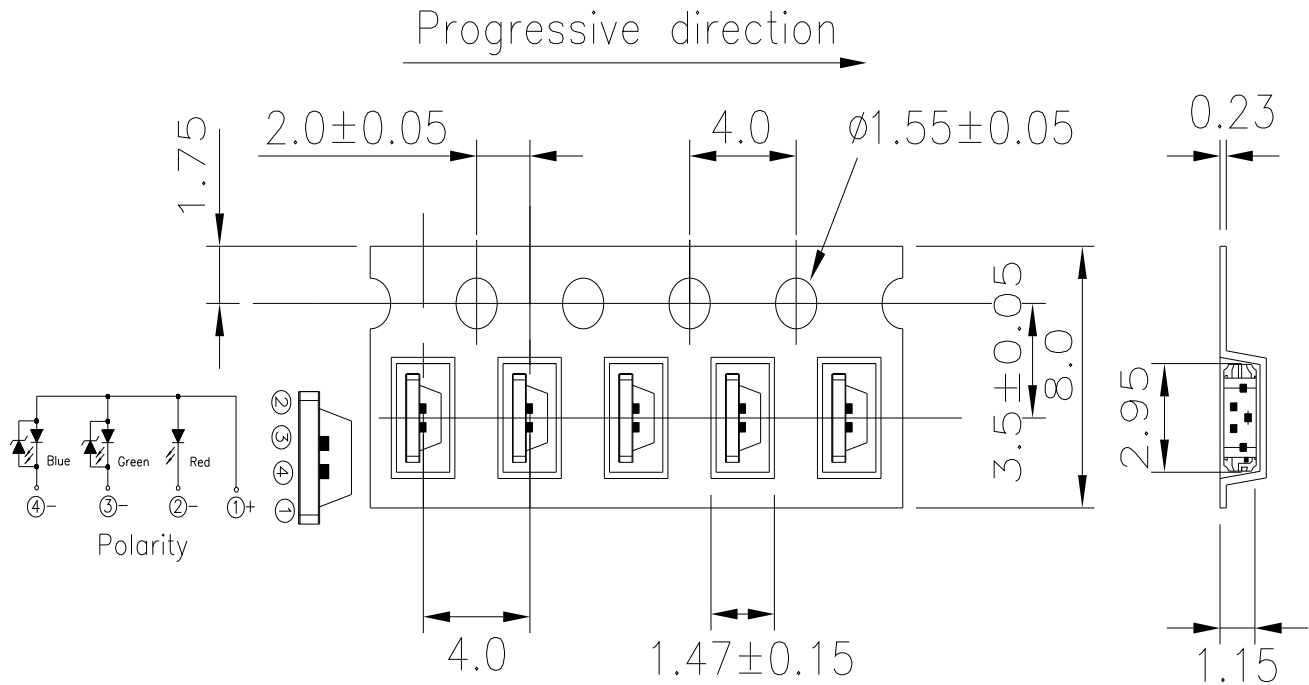
- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

Reel Dimensions



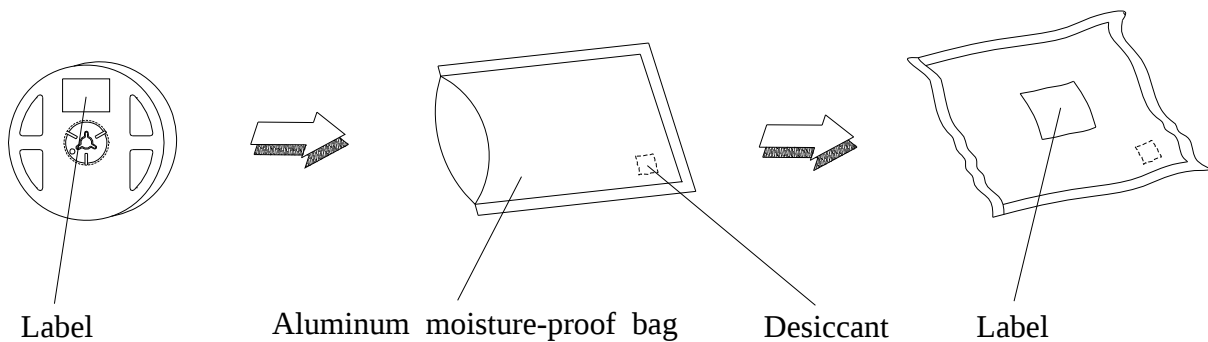
Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit = mm

Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel



Note: Tolerances unless mentioned $\pm 0.1\text{mm}$. Unit = mm

Moisture Resistant Packing Process



Note: Tolerances unless mentioned $\pm 0.1\text{mm}$. Unit = mm

Precautions for Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

2.3 After opening the package: The LED's floor life is 1 year under 30°C or less and 60% RH or less.

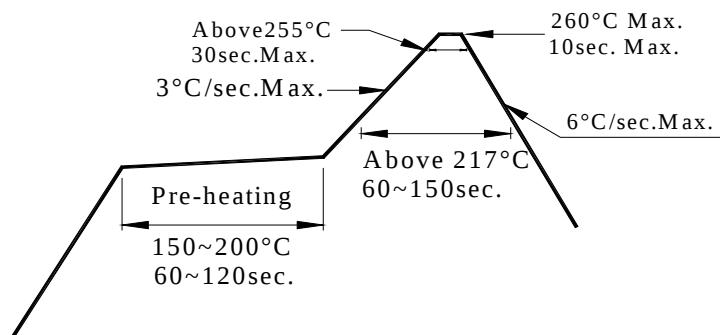
If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

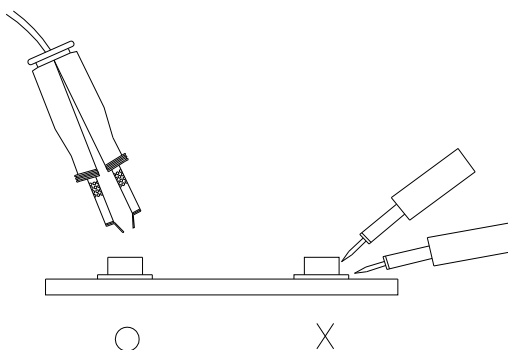
3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight Americas before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.